

Title (en)  
HEAT CONDUCTIVE ALUMINIUM ALLOY AND USE THEREOF

Title (de)  
WÄRMELEITENDE ALUMINIUMLEGIERUNG UND VERWENDUNG DAVON

Title (fr)  
ALLIAGE D'ALUMINIUM THERMOCONDUCTEUR ET SON UTILISATION

Publication  
**EP 3546607 A4 20200129 (EN)**

Application  
**EP 17874325 A 20171025**

Priority

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Abstract (en)  
[origin: EP3546607A1] The present disclosure discloses a thermally conductive aluminum alloy and application thereof. The thermally conductive aluminum alloy contains alloying elements, unavoidable impurities and the balance of an aluminum element. Based on the total weight of the thermally conductive aluminum alloy, the alloying elements include: 5.0 to 11.0 wt% of Si, 0.4 to 1.0 wt% of Fe, 0.2 to 1.0 wt% of Mg, less than 0.1 wt% of Zn, less than 0.1 wt% of Mn, less than 0.1 wt% of Sr and less than 0.1 wt% of Cu. The thermally conductive aluminum alloy prepared by the present disclosure has a tensile strength of not less than 250 MPa, a yield strength of not less than 150 MPa, an elongation of not less than 3.5%, and a thermal conductivity of not less than 150 W/(m•K).

IPC 8 full level  
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**C22C 2202/00** (2013.01 - US)

Citation (search report)

- [X] JP 2006063420 A 20060309 - RYOKA MACS CORP
- [X] EP 1736561 A1 20061227 - NIPPON LIGHT METAL CO [JP]
- See references of WO 2018095186A1

Cited by  
CN113528899A

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**EP 17874325 A 20171025**; CN 201611038514 A 20161123; CN 2017107692 W 20171025; JP 2019527302 A 20171025; KR 20197014544 A 20171025; US 201716463426 A 20171025